



# High Efficiency Linear Regulator

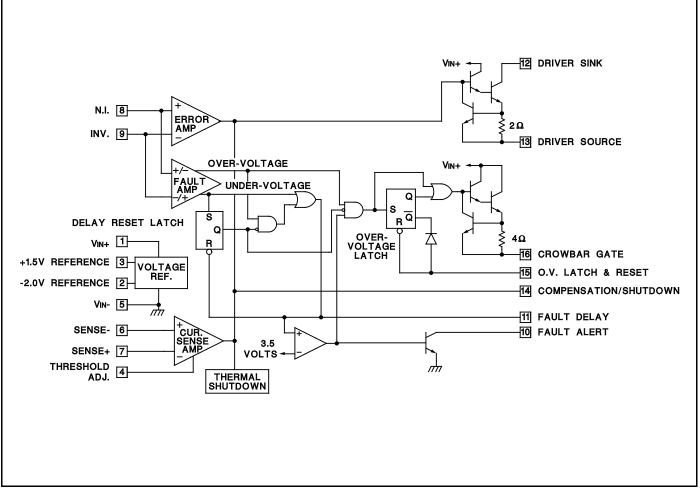
#### FEATURES

- Minimum VIN VOUT Less Than 0.5V At 5A Load With External Pass Device
- Equally Usable For Either Positive or Negative Regulator Design
- Adjustable Low Threshold Current Sense Amplifier
- Under And Over-Voltage Fault Alert With Programmable Delay
- Over-Voltage Fault Latch With 100mA Crowbar Drive Output

## DESCRIPTION

The UC1834 family of integrated circuits is optimized for the design of low input-output differential linear regulators. A high gain amplifier and 200mA sink or source drive outputs facilitate high output current designs which use an external pass device. With both positive and negative precision references, either polarity of regulator can be implemented. A current sense amplifier with a low, adjustable, threshold can be used to sense and limit currents in either the positive or negative supply lines.

In addition, this series of parts has a fault monitoring circuit which senses both under and over-voltage fault conditions. After a user defined delay for transient rejection, this circuitry provides a fault alert output for either fault condition. In the over-voltage case, a 100mA crowbar output is activated. An over-voltage latch will maintain the crowbar output and can be used to shutdown the driver outputs. System control to the device can be accommodated at a single input which will act as both a supply reset and remote shutdown terminal. These die are protected against excessive power dissipation by an internal thermal shutdown function.



#### BLOCK DIAGRAM

#### ABSOLUTE MAXIMUM RATINGS (Note 1)

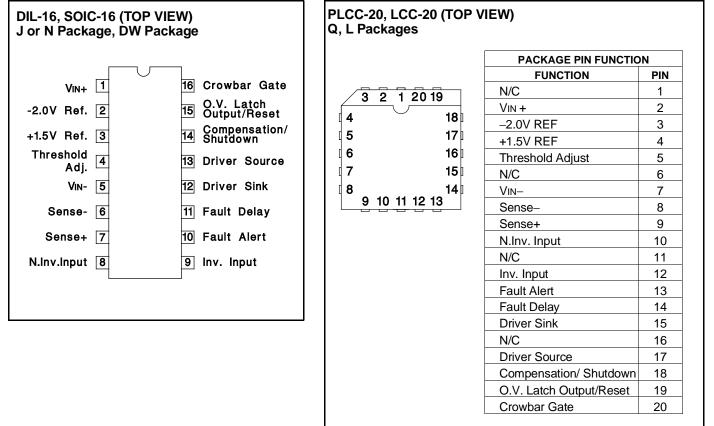
Input Supply Voltage, V <sub>IN</sub> +
Driver Current
Driver Source to Sink Voltage 40V
Crowbar Current
+1.5V Reference Output Current
Fault Alert Voltage 40V
Fault Alert Current 15mA
Error Amplifier Inputs –0.5V to 35V
Current Sense Inputs –0.5V to 40V
O.V. Latch Output Voltage –0.5V to 40V
O.V. Latch Output Current 15mA

Power Dissipation at TA = 25°C 1000mW
1
Power Dissipation at Tc = 25°C 2000mW
Operating Junction Temperature –55°C to +150°C
Storage Temperature
Lead Temperature (soldering, 10 seconds) 300°C
Note 1: Voltages are reference to VIN–, Pin 5.
Currents are positive into pagative out of the specified

Currents are positive into, negative out of the specified terminals. Consult Packaging section of Databook for thermal

limitations and considerations of package.

#### **CONNECTION DIAGRAMS**



**ELECTRICAL CHARACTERISTICS:** Unless otherwise stated, these specifications apply for TA=-55°C to +125°C for the UC1834, -40°C to +85°C for the UC2834, and 0°C to +70°C for the UC3834. VIN+ = 15V, VIN- = 0V, TA = TJ.

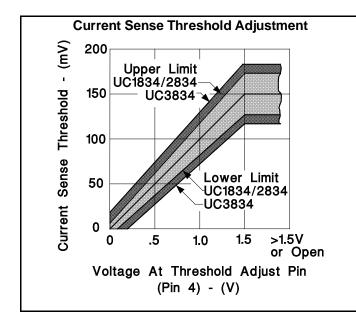
PARAMETER	TEST CONDITIONS		UC1834 UC2834	L L		UC3834	ļ	UNITS
		MIN	TYP	MAX	MIN	TYP	MAX	
Turn-on Characteristics								
Standby Supply Current			5.5	7		5.5	10	mA
+1.5 Volt Reference								
Output Voltage	TJ = 25°C	1.485	1.5	1.515	1.47	1.5	1.53	V
	$T_{J}(MIN) \leq T_{J} \leq T_{J}(MAX)$	1.47		1.53	1.455		1.545	
Line Regulation	VIN+ = 5 to 35V		1	10		1	15	mV
Load Regulation	IOUT = 0 to $2mA$		1	10		1	15	mV
-2.0 Volt Reference (Note 2)			1			1		
Output Voltage (Referenced	$T_J = 25^{\circ}C$	-2.04	-2	-1.96	-2.06	-2	-1.94	V
to ViN⁺)	$T_{J}(MIN) \le T_{J} \le T_{J}(MAX)$	-2.06		-1.94	-2.08		-1.92	
Line Regulation	VIN+ = 5 to 35V		1.5	15		1.5	20	mV
Output Impedance			2.3			2.3		kΩ
Error Amplifier Section		-						-
Input Offset Voltage	Vсм = 1.5V		1	6		1	10	mV
Input Bias Current	Vсм = 1.5V		-1	-4		-1	-8	μA
Input Offset Current	Vсм = 1.5V		0.1	1		0.1	2	μA
	Output @ Pin 14, Pin 12 = VIN+ Pin 13, 20 $\Omega$ to VIN–	50	65		50	65		dB
CMRR	Vсм = 0.5 to 33V, V <sub>IN</sub> + = 35V	60	80		60	80		dB
PSRR	VIN+ = 5 to 35V, VCM = 1.5V	70	100		70	100		dB
Driver Section	· · · · ·							
Maximum Output Current		200	350		200	350		mA
Saturation Voltage	IOUT = 100mA		0.5	1.2		0.5	1.5	V
Output Leakage Current	Pin 12 = 35V, Pin 13 = VIN-, Pin 14 = VIN-		0.1	50		0.1	50	μA
Shutdown Input Voltage at Pin 14	IOUT $\leq$ 100µA, Pin 13 = VIN-, Pin 12 = VIN+	0.4	1		0.4	1		V
Shutdown Input Current at Pin 14	Pin 14 = VIN–, Pin 12 = VIN+ Ιουτ ≤ 100μΑ, Pin 13 = VIN–		-100	-150		-100	-150	μA
Thermal Shutdown (Note 3)			165			165		°C
Fault Amplifier Section		•						
Under- and Over-Voltage Fault Threshold	VCM = 1.5V, @ E/A Inputs	120	150	180	110	150	190	mV
Common Mode Sensitivity	VIN+ = 35V, VCM = 1.5 to 33V		-0.4	-0.8		-0.4	-1.0	%/v
Supply Sensitivity	VCM = 1.5V, VIN+ = 5 to 35V		-0.5	-1.0		-0.5	-1.2	%/V
Fault Delay		30	45	60	30	45	60	ms/μF
Fault Alert Output Current		2	5		2	5		mA
Fault Alert Saturation Voltage	IOUT = 1mA		0.2	0.5		0.2	0.5	V
O.V. Latch Output Current		2	4		2	4		mA
O.V. Latch Saturation Voltage	IOUT = 1mA		1.0	1.3		1.0	1.3	V
O.V. Latch Output Reset Voltage		0.3	0.4	0.6	0.3	0.4	0.6	V
Crowbar Gate Current		-100	-175		-100	-175		mA
Crowbar Gate Leakage Current	VIN+ = 35V, Pin 16 = VIN-		-0.5	-50		-0.5	-50	μA

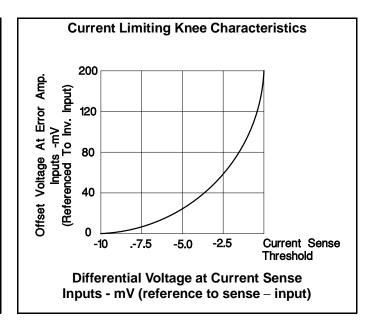
Note 2: When using both the 1.5V and -2.0V references the current out of pin 3 should be balanced by an equivalent current into Pin 2. The -2.0V output will change -2.3mV per  $\mu$ A of imbalance.

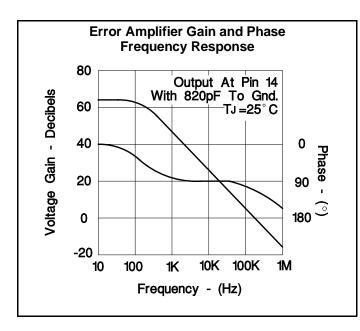
Note 3: Thermal shutdown turns off the driver. If Pin 15 (O.V. Latch Output) is tied to Pin 14 (Compensation/Shutdown) the O.V. Latch will be reset.

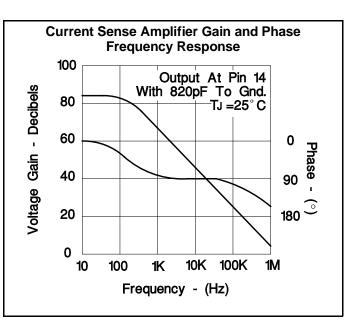
**ELECTRICAL CHARACTERISTICS:** Unless otherwise stated, these specifications apply for TA=-55°C to +125°C for the UC1834, -40°C to +85°C for the UC2834, and 0°C to +70°C for the UC3834. VIN+ = 15V, VIN- = 0V. TA = TJ

PARAMETER	TEST CONDITIONS		UC1834 UC2834			UNITS		
		MIN	TYP	MAX	MIN	TYP	MAX	
<b>Current Sense Amplifier Section</b>	on							
Threshold Voltage	Pin 4 Open, Vcм = VIN+ or VIN-	130	150	170	120	150	180	mV
	Pin 4 = 0.5V, $V_{CM}$ = VIN+ or VIN-	40	50	60	30	50	70	
Threshold Supply Sensitivity	Pin 4 Open, VCM = VIN-, VIN+ = 5 to 35V		-0.1	-0.3		-0.1	-0.5	%/V
Adj. Input Current	Pin 4 = 0.5V		-2	-10		-2	-10	μA
Sense Input Bias Current	VCM = VIN+		100	200		100	200	μA
	VCM = VIN-		-100	-200		-100	-200	

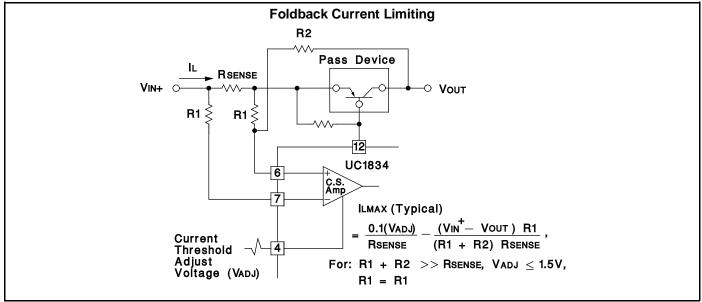








#### **APPLICATION INFORMATION**



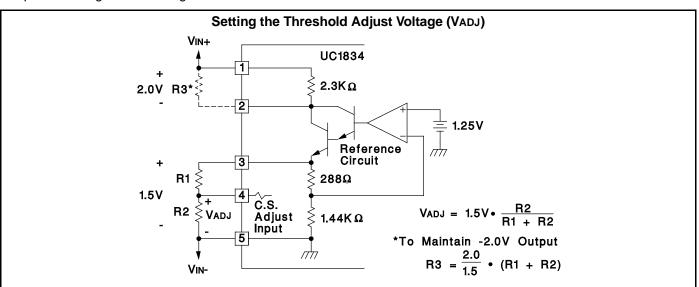
Both the current sense and error amplifiers on the UC1834 are transconductance type amplifiers. As a result, their voltage gain is a direct function of the load impedance at their shared output pin, Pin 14. Their small signal voltage gain as a function of load and frequency is nominally given by;

$$Av E/A = \frac{Z_L(f)}{700\Omega} \text{ and } Av C. S./A = \frac{Z_L(f)}{70\Omega}$$
  
for:  $f \le 500 \text{kHz}$  and  $|Z_L(f)| \le 1 M\Omega$ 

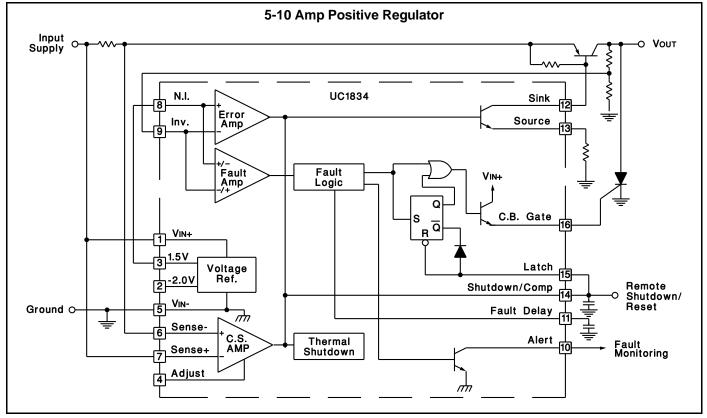
Where:

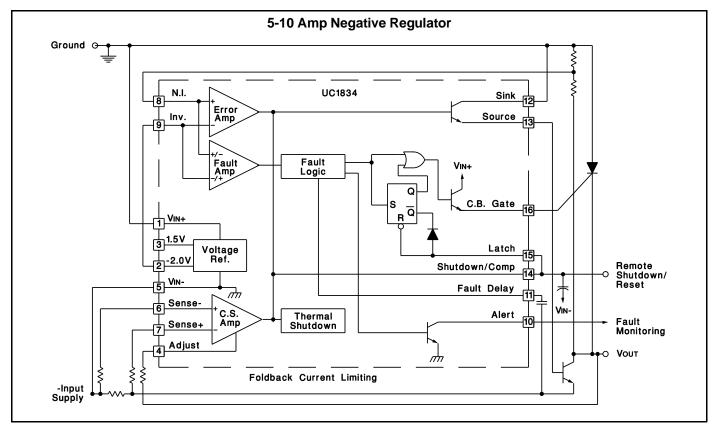
Av=Small Signal Voltage Gain to pin 14. ZL(f) = Load Impedance at Pin 14.

The UC1834 fault delay circuitry prevents the fault outputs from responding to transient fault conditions. The delay reset latch insures that the full, user defined, delay passes before an over-voltage fault response occurs. This prevents unnecessary crowbar, or latched-off conditions, from occurring following sharp under-voltage to over-voltage transients. The crowbar output on the UC1834 is activated following a sustained over-voltage condition. The crowbar output remains high as long as the fault condition persists, or, as long as the over-voltage latch is set. The latch is set with an over-voltage fault if the voltage at Pin 15 is above the latch reset threshold, typically 0.4V. When the latch is set, its Q- output will pull Pin 15 low through a series diode. As long as a nominal pull-up load exists, the series diode prevents Q- from pulling Pin 15 below the reset threshold. However, Pin 15 is pulled low enough to disable the driver outputs if Pins 15 and 14 are tied together. With Pin 15 and 14 common, the regulator will latch off in response to an over-voltage fault. If the fault condition is cleared and Pins 14 and 15 are momentarily pulled below the latch reset threshold, the driver outputs are re-enabled.



#### **TYPICAL APPLICATIONS**





UNITRODE CORPORATION 7 CONTINENTAL BLVD. • MERRIMACK, NH 03054 TEL. (603) 424-2410 • FAX (603) 424-3460 TEXAS INSTRUMENTS

17-Oct-2008

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-87742012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8774201EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
UC1834J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
UC1834J/81025	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
UC1834J883B	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
UC1834L	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
UC1834L883B	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
UC2834DW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2834DWG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2834DWTR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2834DWTRG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2834J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
UC2834N	ACTIVE	PDIP	Ν	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC2834NG4	ACTIVE	PDIP	Ν	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC2834Q	ACTIVE	PLCC	FN	20	46	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC2834QG3	ACTIVE	PLCC	FN	20	46	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC2834QTR	ACTIVE	PLCC	FN	20	1000	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC2834QTRG3	ACTIVE	PLCC	FN	20	1000	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC3834DW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3834DWG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3834N	ACTIVE	PDIP	Ν	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC3834NG4	ACTIVE	PDIP	Ν	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered



at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### OTHER QUALIFIED VERSIONS OF UC1834, UC2834, UC2834M, UC3834 :

• Space: UC1834-SP

NOTE: Qualified Version Definitions:

• Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

#### TAPE AND REEL INFORMATION





## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*A	Il dimensions are nominal												
	Device	-	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	UC2834DWTR	SOIC	DW	16	2000	330.0	16.4	10.85	10.8	2.7	12.0	16.0	Q1
	UC2834QTR	PLCC	FN	20	1000	330.0	16.4	10.3	10.3	4.9	12.0	16.0	Q1



# PACKAGE MATERIALS INFORMATION

6-Oct-2008



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UC2834DWTR	SOIC	DW	16	2000	346.0	346.0	33.0
UC2834QTR	PLCC	FN	20	1000	346.0	346.0	33.0

#### **IMPORTANT NOTICE**

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Clocks and Timers	www.ti.com/clocks	Digital Control	www.ti.com/digitalcontrol
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
RFID	www.ti-rfid.com	Telephony	www.ti.com/telephony
RF/IF and ZigBee® Solutions	www.ti.com/lprf	Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2008, Texas Instruments Incorporated